

TnG Technology Corporation

PCB Design Team

Integration Services

- Electronic product design

System design

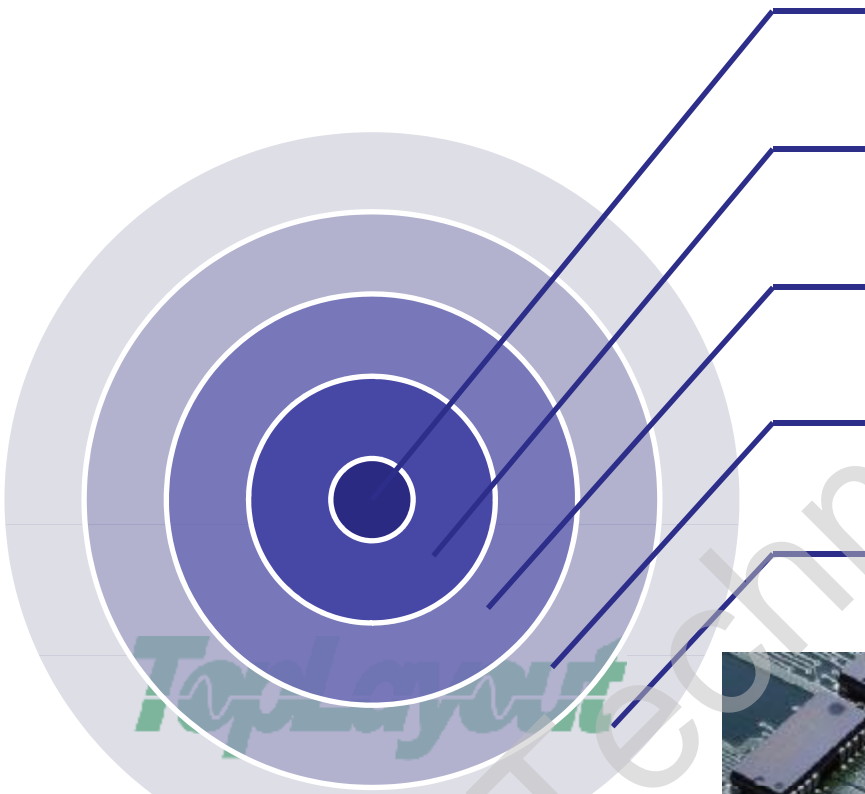
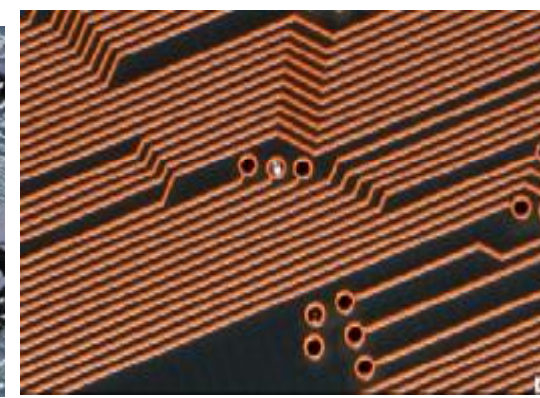
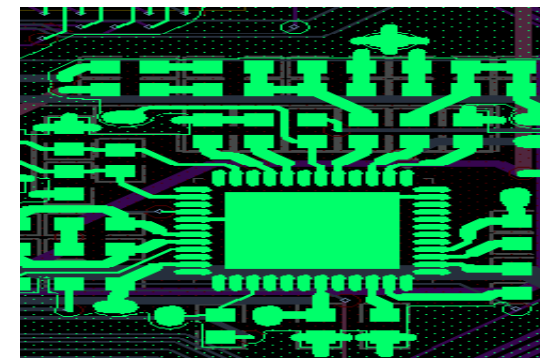
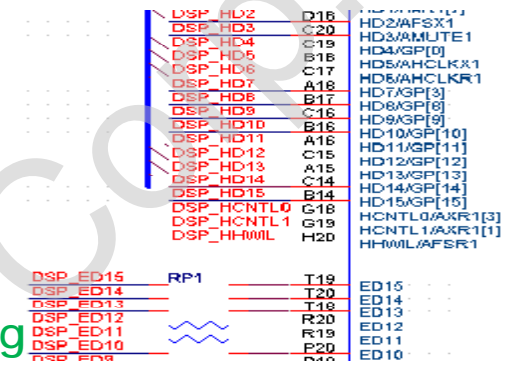
Software design

Schematic Drawing

PCB design

PCB fabrication

PCB Assembly



Key Tech.

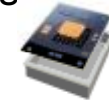
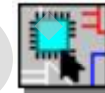


PCB Design Tools:
Cadence: Allegro

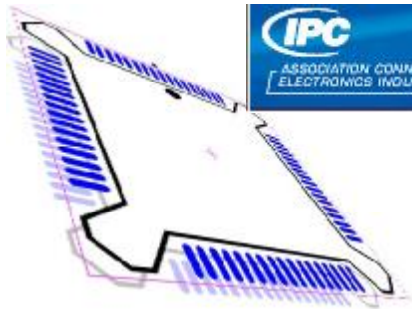


Support Schematics:

OrCAD
PowerLogic
Altium

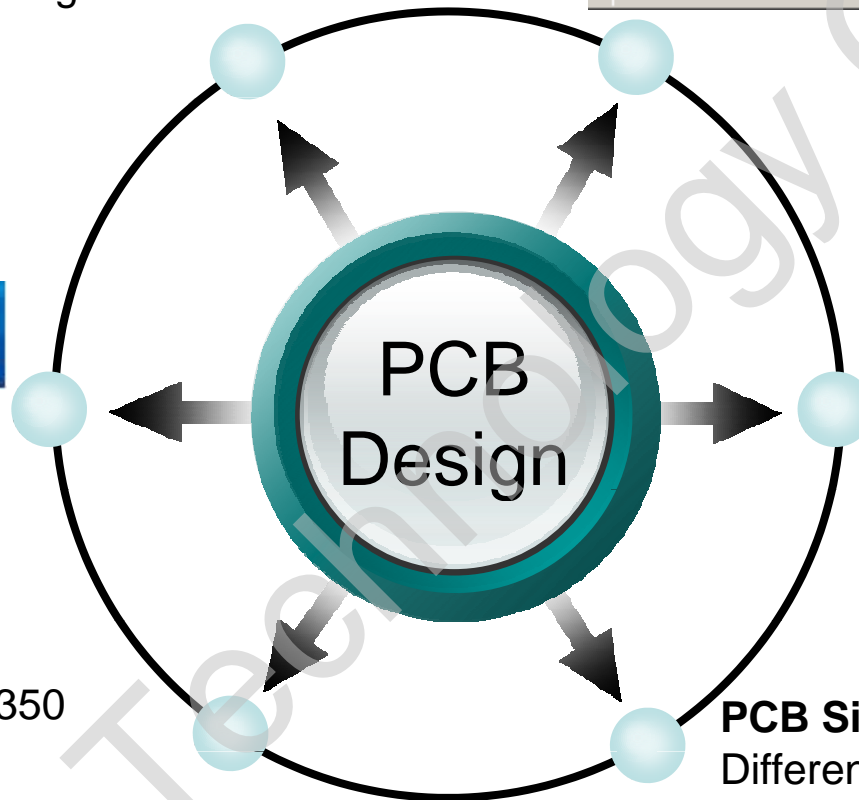


**PCB Library
Design Team**



DFM Team

Valor, Genisis, CAM350

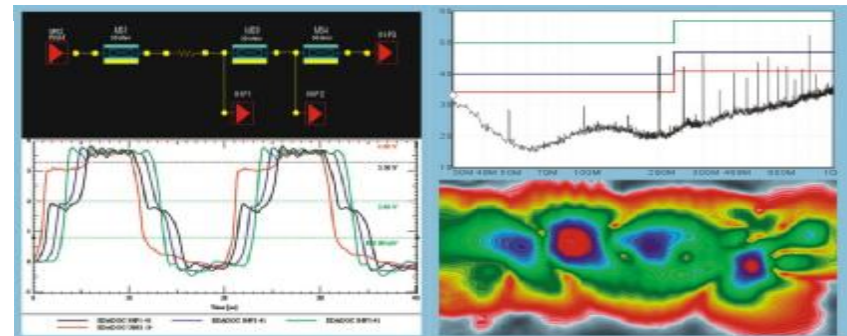
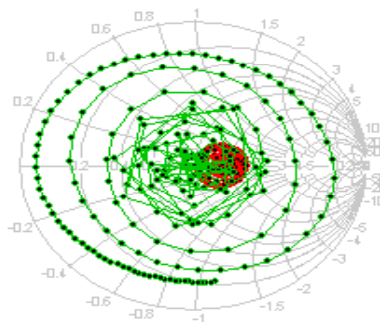


**Process management
System**



PCB Simulation:

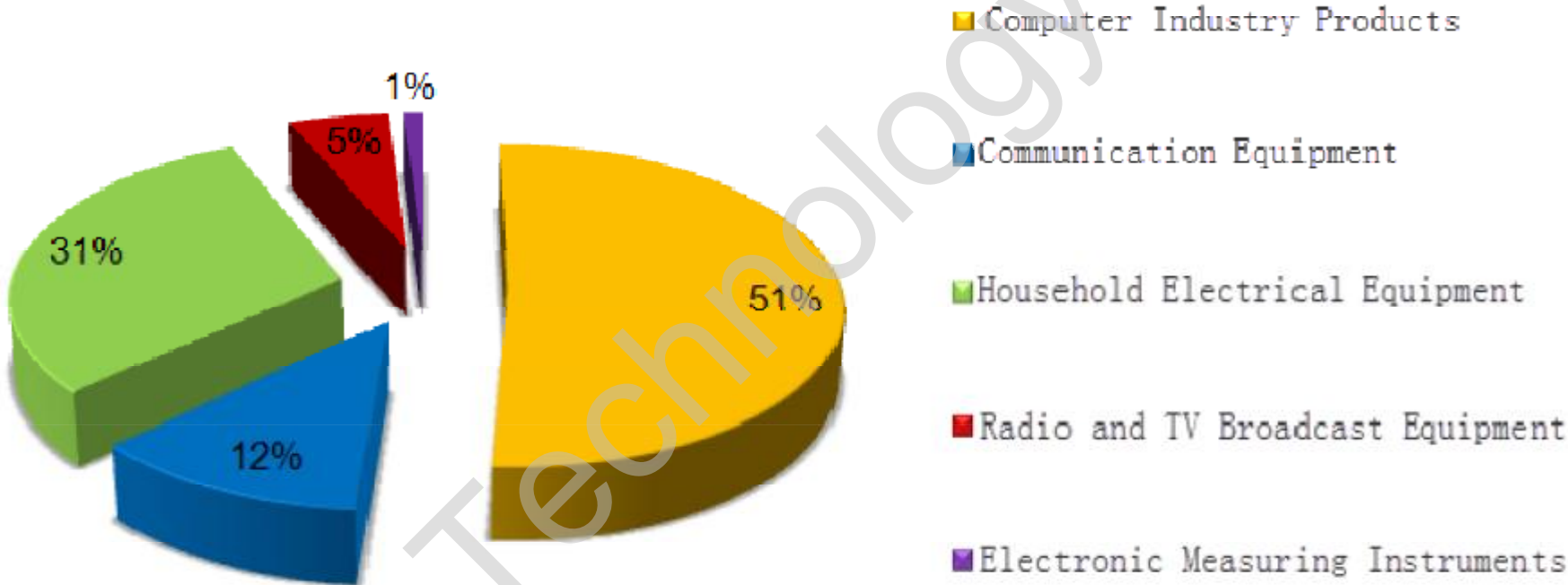
Differential Impedance, SI, PI, EMI



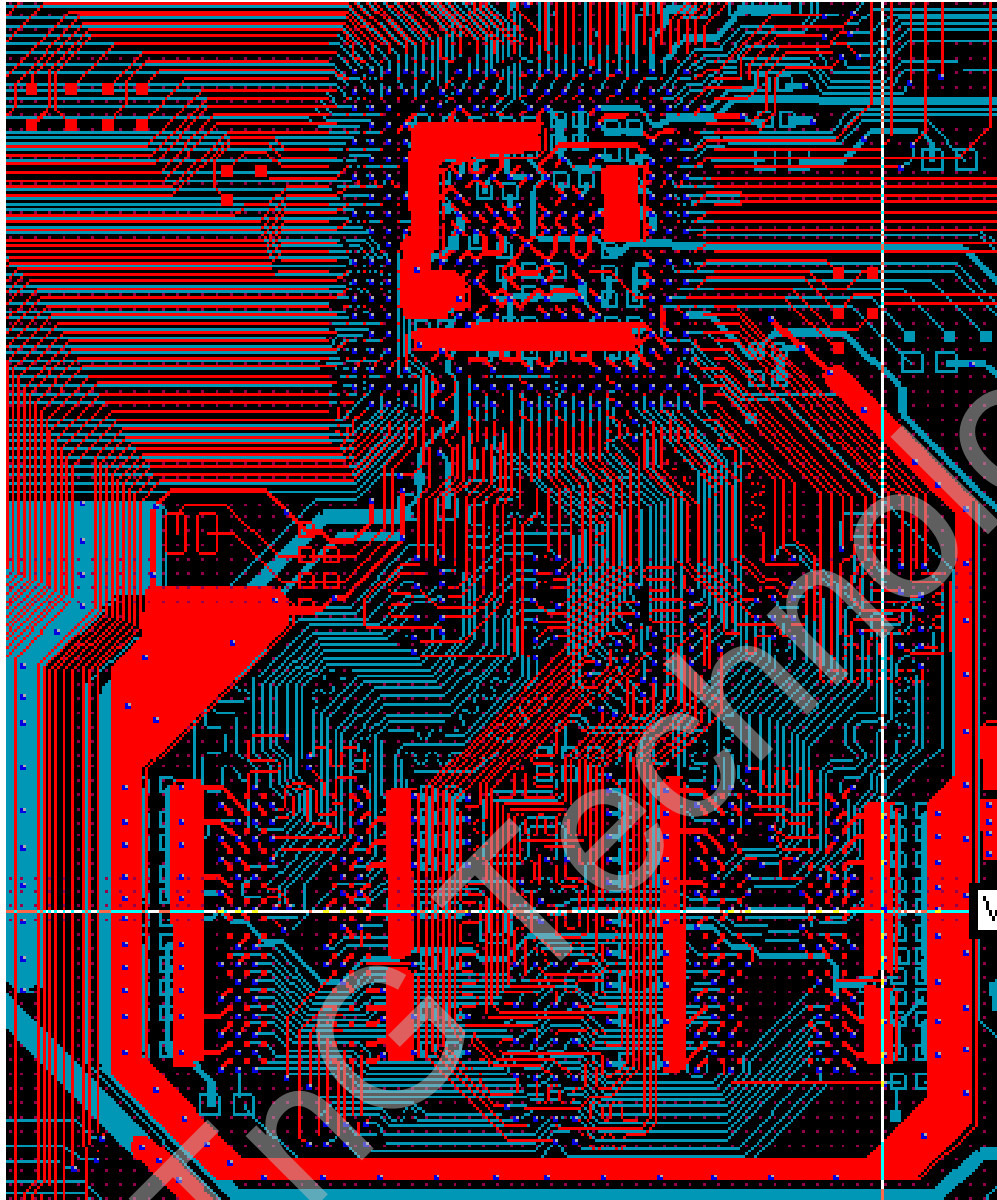
PCB Design Experience

- Ø High Layer count boards : 22+ layers
- Ø High Density PCBs : > 500 pins / inch²
- Ø High Speed Interconnects : 10 GHz differential signals
- Ø Impedance control/Delay matching/Bus topology
- Ø Minimum BGA Pin pitch: 0.5mm(BGA, CSP)
- Ø Blind and buried via

PCB Design Experience

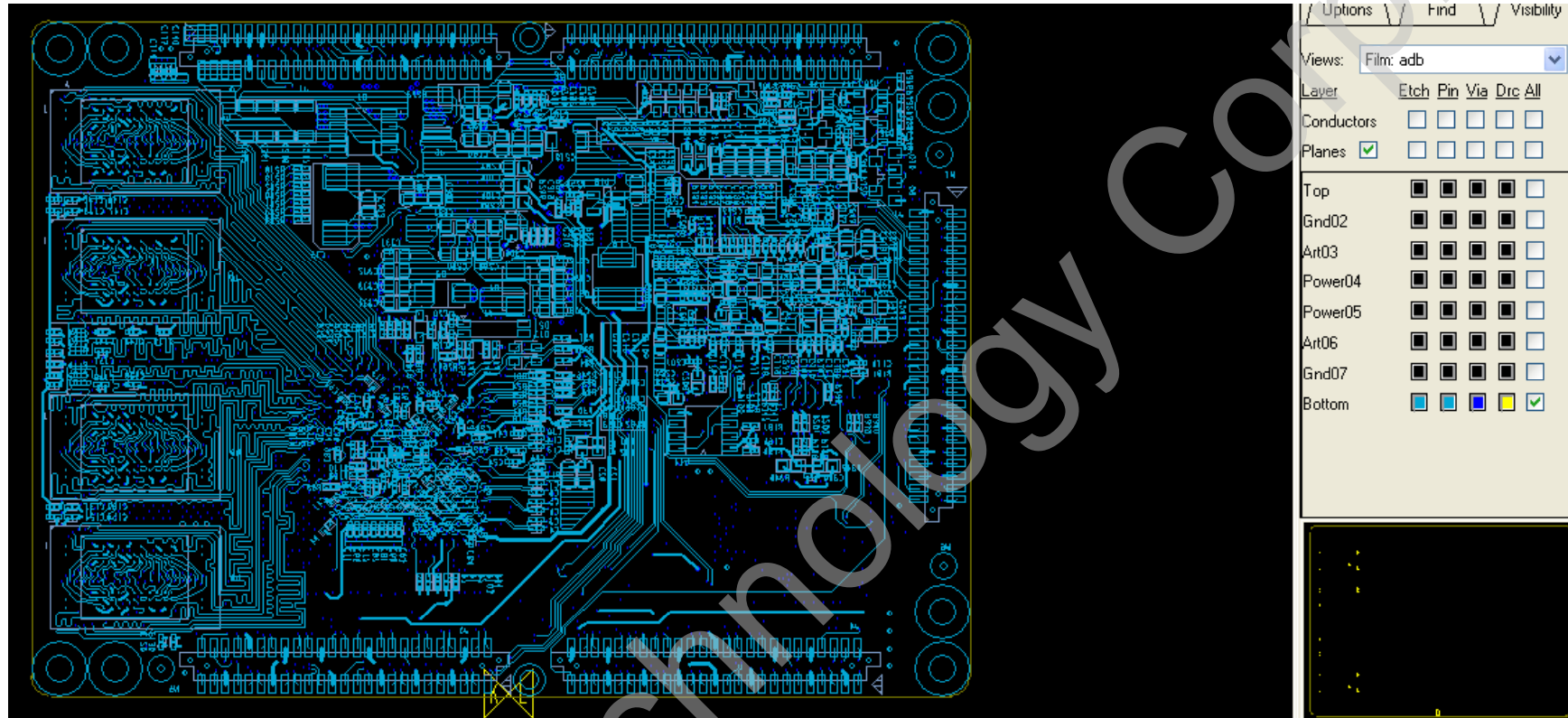


PCB Design Samples



全智A10平板，原廠
6層，改4層，一次
成功。

難點：BGA出線難，
只有2層出線，採用
交錯打孔多出線；
DDR3阻抗控制難，
等長控制難，採用
分段集中打孔



高密度的且有8顆ddr3疊在一起的消費通信板轉接板
High density communication board with 8 DDR3